

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Taylor R. Efland**

Docket No.: **TI-30963.1**

Serial No.: **TBD**

Examiner: **TBD**

Filed: **Herewith**


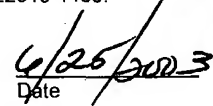
Art Unit.: **TBD**

For: **Thermally Enhanced Semiconductor Chip
Having Integrated Bonds Over Active
Circuits**

Conf. No.: **TBD**

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner For Patents
Attn: Official Drafts Person
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.	
 Elizabeth Austin	 Date

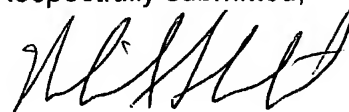
Dear Sir:

Submitted herewith are 2 sheets of formal drawings.

No fee is believed by Applicant to be due; however, the Commissioner is hereby authorized and requested to charge any necessary fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-5653

Respectfully submitted,



Michael K. Skrehot
Attorney for Applicants
Reg. No.: 36,682